

**AMENDMENT TO THE CLAIMS****Claims 1-25 (Cancelled)**

26. (Currently Amended) An electronic component to be mounted on a printed board, said electronic component comprising:

an electrical connecting surface;

a plurality of electrical connecting portions provided on said electrical connecting surface in arrangement positions within a contour of said electronic component; and

at least one recognition mark located on a surface of the electronic component and serving as a reference for the arrangement positions of said electrical connecting portions.

27. (Previously Presented) An electronic component as claimed in claim 26, wherein said at least one recognition mark comprises a pair of recognition marks positioned symmetrically with respect to a center point of said electrical connecting surface, wherein said electrical connecting portions are disposed in an array that surrounds said recognition marks.

28. (Previously Presented) An electronic component as claimed in claim 26, wherein said at least one recognition mark comprises a plurality of recognition marks that

are positioned symmetrically with respect to a center point of said electrical connecting surface, wherein said recognition marks are located in a central portion of said electrical connecting surface, and said electrical connecting portions are disposed around said recognition marks.

29. (Previously Presented) An electronic component as claimed in claim 26, wherein said recognition mark is provided on a side of said electrical connecting surface that is adapted to confront a mounting position of the printed board.

30. (Previously Presented) An electronic component as claimed in claim 29, wherein said recognition mark comprises a projection or a printed symbol.

31. (Currently Amended) An electronic component ~~as claimed in claim 29,~~  
to be mounted on a printed board, said electronic component comprising:

an electrical connecting surface;

a plurality of electrical connecting portions provided on said electrical connecting surface in arrangement positions; and

at least one recognition mark located on a surface of the electronic component and serving as a reference for the arrangement positions of said electrical connecting portions,

wherein said recognition mark includes coded information indicative of said electronic component.

32. (Previously Presented) An electronic component as claimed in claim 31, wherein the coded information of said recognition mark is information concerned with a state in which the electrical connecting portions are formed.

33. (Previously Presented) An electronic component as claimed in claim 26, wherein said recognition mark is located in a corner portion of an opposite side of the electronic component relative to said electrical connecting portions.

34. (Previously Presented) An electronic component as claimed in claim 26, wherein said recognition mark is formed on said electrical connecting surface simultaneously with said electrical connecting portions.

35. (Previously Presented) An electronic component as claimed in claim 26, wherein said electrical connecting portions are solder bumps.

36. (Previously Presented) An electronic component as claimed in claim 26, wherein said electrical connecting portions are lands.

37-47. (Cancelled)

48. (New) An electronic component as claimed in claim 26, wherein the recognition mark does not project from the surface of the electronic component.